

11017 U.S. PTO  
10/077538

02/15/02

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PATENT NUMBER and  
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM 10077538	FILING DATE 02/15/2002	CLASS 36129	SUBCLASS 832	GAU 3729 2841	EXAMINER Arbes
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\*\*APPLICANTS: Yee Lup; Belmas Darrell;

\*\*CONTINUING DATA VERIFIED:

\*\* FOREIGN APPLICATIONS VERIFIED:

PG-PUB DO NOT PUBLISH ☐

RESCIND ☐

Foreign priority claimed ☐ yes ☐ no

35 USC 119 conditions met ☐ yes ☐ no

Verified and Acknowledged Examiners's initials

ATTORNEY DOCKET NO

SC11328ZK

TITLE : Process and apparatus for disengaging semiconductor die from an adhesive film

U.S. DEPT. OF COMM./PAT. & TM.-PTO-4361 (Rev. 12-94)

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NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
Assistant Examiner		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs.Drwg. Print Fig.
Primary Examiner		Application Examiner	
PREPARED FOR ISSUE			
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